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Paper Code : OE-601C/OE-EE601C VLSI And Micro Electronics

UPID : 006748

Time Allotted : 3 Hours

Full Marks : 70

The Figures in the margin indicate full marks.

Candidate are required to give their answers in their own words as far as practicable

## Group-A (Very Short Answer Type Question)

1. Answer any ten of the following :

[ 1 x 10 = 10 ]

- (I) Two-input NAND gate requires six transistors in static CMOS logic. ( True / False ).
- (II) Upon exposure, the positive photoresist becomes \_\_\_\_\_ soluble in the developer solution.
- (III) In VHDL , the process statement is a sequential statement.(True / False)
- (IV) What are the major advantages of the IC over discrete component based circuits ?
- (V) Polysilicon is used for gate in MOSFET because it has lattice matching with Si. ( True / False ).
- (VI) Unit of sheet resistance is \_\_\_\_\_.
- (VII) Pull-down network ( PDN ) connects output node to \_\_\_\_\_ .
- (VIII) If the value of segregation coefficient is greater than one, it signifies that the dopant concentration is more in solid than liquid. ( True / False ).
- (IX) In VHDL, the '&' operator indicates \_\_\_\_\_ operation.
- (X) State Moore's law
- (XI) In combinational logic circuit, the output is determined by present logic inputs. ( True / False ).
- (XII) Dry etching is used when vertical side walls are required. ( True / False ).

## Group-B (Short Answer Type Question)

Answer any three of the following :

[ 5 x 3 = 15 ]

2. Define regularity , modularity and locality. [5]
3. Discuss the MOS system with C-V characteristics. [5]
4. Draw the flow diagram of typical VLSI design flow and explain. [5]
5. Explain with diagram, the operation of Enhancement type pMOS Transistor. [5]
6. Write Verilog program for (a) two-input AND gate & (b) latch. [5]

## Group-C (Long Answer Type Question)

Answer any three of the following :

[ 15 x 3 = 45 ]

7. Deduce the MOSFET drain current equations of a n-type MOSFET for linear and saturation region keeping substrate bias effect. [ 15 ]
8. What is Epitaxial Growth ? Explain their various methods. [ 15 ]
9. (a) Discuss about advantages and disadvantages of MOSFET scaling. [ 7 ]  
(b) Explain narrow channel effects of MOSFET. [ 8 ]
10. (a) What is oxidation ? Explain its various methods. [ 9 ]  
(b) Discuss about (a) thin oxide and (b) thick oxide. [ 6 ]
11. (a) How IC's are classified ? Explain. [ 8 ]  
(b) Briefly describe about VLSI design methodology. [ 7 ]

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